

### SLOVENSKI STANDARD SIST EN IEC 62769-100:2021

01-februar-2021

Vključitev procesne terenske naprave (FDI) - 100. del: Profili - Splošni protokoli (IEC 62769-100:2020)

Field device integration (FDI) - Part 100: Profiles - Generic protocolsi (IEC 62769-100:2020)

Feldgeräteintegration (FDI) - Teil 100: Profile - Allgemeine Protokolle (IEC 62769-100:2020)

iTeh STANDARD PREVIEW

Intégration des appareils de terrain (FDI) - Partie 100. Profils - Protocoles génériques (IEC 62769-100:2020)

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Ta slovenski standard je istoveten z. 9/sist-EN IEC 62769-100:2020

#### ICS:

25.040.40 Merjenje in krmiljenje Industrial process industrijskih postopkov measurement and control

35.240.50 Uporabniške rešitve IT v IT applications in industry industriji

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EUROPEAN STANDARD NORME EUROPÉENNE EUROPÄISCHE NORM **EN IEC 62769-100** 

November 2020

ICS 25.040.40; 35.100.05

#### **English Version**

Field device integration (FDI) - Part 100: Profiles - Generic protocols (IEC 62769-100:2020)

Intégration des appareils de terrain (FDI) - Partie 100: Profils - Protocoles génériques (IEC 62769-100:2020)

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Feldgeräteintegration (FDI) - Teil 100: Profile - Allgemeine Protokolle (IEC 62769-100:2020)

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EN IEC 62769-100:2020 (E)

#### **European foreword**

The text of document 65E/739/FDIS, future edition 1 of IEC 62769-100, prepared by SC 65E "Devices and integration in enterprise systems" of IEC/TC 65 "Industrial-process measurement, control and automation" was submitted to the IEC-CENELEC parallel vote and approved by CENELEC as EN IEC 62769-100:2020.

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### Annex ZA (normative)

## Normative references to international publications with their corresponding European publications

The following documents are referred to in the text in such a way that some or all of their content constitutes requirements of this document. For dated references, only the edition cited applies. For undated references, the latest edition of the referenced document (including any amendments) applies.

NOTE 1 Where an International Publication has been modified by common modifications, indicated by (mod), the relevant EN/HD applies.

NOTE 2 Up-to-date information on the latest versions of the European Standards listed in this annex is available here: www.cenelec.eu.

<u>Publication</u>	<u>Year</u>	<u>Title</u>	EN/HD	<u>Year</u>
IEC 61804	series	Function blocks (FB) for process control and electronic device description language (EDDL)	EN IEC 61804	series
IEC 61804-3	https://s	Devices and integration in enterprise systems - Function blocks (FB) for process control and electronic device description language (EDDL) - Part 3: EDDL syntax and semantics 18.1 EV 16.2769-100:2021 standards.iteh.ai/catalog/standards/sist/a0594268-c994-4b	EN IEC 61804-3	-
IEC 62541-100	2015	OPC Unified Architecture - Part 100: Device Interface	EN 62541-100	2015
IEC 62769-2	-	Field Device Integration (FDI) - Part 2: FDI Client	-	-
IEC 62769-4	-	Field Device Integration (FDI) - Part 4: FDI Packages	-	-
IEC 62769-5	-	Field Device Integration (FDI) - Part 5: FDI Information Model	-	-
IEC 62769-7	-	Field Device Integration (FDI) - Part 7: FDI Communication Devices	-	-

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IEC 62769-100

Edition 1.0 2020-09

### INTERNATIONAL STANDARD

### NORME INTERNATIONALE

Field device integration (FDI) ANDARD PREVIEW Part 100: Profiles – Generic protocols ds.iteh.ai)

Intégration des appareils de terrain (FDI) 69-100:2021

Partie 100: Profils # Protocoles génériques t/a0594268-c994-4be0-bdde-

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INTERNATIONAL ELECTROTECHNICAL COMMISSION

COMMISSION ELECTROTECHNIQUE INTERNATIONALE

ICS 25.040.40; 35.100.05 ISBN 978-2-8322-8858-0

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#### CONTENTS

FC	FOREWORD4			
1	Scop	e	6	
2	Norm	ative references	6	
3	Term	s, definitions, abbreviated terms and conventions	6	
	3.1	Abbreviated terms	7	
	3.2	Conventions	7	
	3.2.1	EDDL syntax	7	
	3.2.2	•		
	3.2.3	•		
4	Profil	e for Generic Protocols		
	4.1	General	8	
	4.2	Catalog profile		
	4.2.1	Protocol support file	8	
	4.2.2	• •		
	4.2.3	Profile device	8	
	4.2.4	Protocol version information	9	
	4.3	Associating a Package with a device	9	
	4.3.1	Associating a Package with a device.  Device type identification mapping	9	
	4.3.2			
	4.4	Device type revision mapping content in the second mapping content	10	
	4.4.1	ProtocolType definition: EN IEC 62769-100:2021		
	4.4.2			
	4.4.3	0.4 # 0.01 10.01 1	11	
	4.5	Topology elements	12	
	4.5.1	ConnectionPoint definition	12	
	4.5.2	Communication Device definition	13	
	4.5.3	Communication service provider definition	14	
	4.5.4	Network definition	14	
	4.6	Methods	15	
	4.6.1	Methods for FDI Communication Servers	15	
	4.6.2	Methods for Gateways	19	
	4.6.3	Transfer service parameters	26	
Ar	inex A (	normative) Topology Scan result schema	27	
	A.1	General	27	
	A.2	Network	27	
	A.3	GenericNetworkT	27	
	A.4	GenericConnectionPointT	27	
	A.5	GenericIdentificationT	28	
	A.6	GenericAddressT	29	
Ar	inex B (	normative) Transfer service parameters	30	
	B.1	General	30	
	B.2	sendData	30	
	B.3	receiveData	30	
	B.4	TransferSendDataT	30	
	B.5	EddDataTypeInfoListT	31	

B.6	EddDataTypeInfoT	31
B.7	EddDataTypeT	
B.8	TransferResultDataT	33
Annex C	(normative) Protocol-specific definitions	
C.1	General	
C.2	Header	
C.3	Protocolldentifier	
C.4	Address	
C.5	Manufacturer	
C.6 C.7	DeviceModel	
C.7 C.8	DeviceRevision	
C.8	Tag	
C.10	ProfileId	
C.11	Version	
C.12	ProtocolSupportFile	
	ohy	
Table 1 –	ProtocolSupportFile for FDI Device Packages	8
Table 2 –	Catalog values for profile devices	9
Table 3 –	Catalog values for profile devices  Device identification information mapping PREVIEW	10
	Device revision information mapping: s.iteh.ai.	
Table 5 –	Protocol type GenericProtocol	11
Table 6 –	Inherited DeviceType property mapping 9-100:2021	11
Table 7 –	Inherited DeviceType property mapping 69-100:2021 https://standards.tich.ai/catalog/standards/sist/a0594268-c994-4be0-bdde- Generic Protocol Device Types identification attributes	12
	ConnectionPoint type for Generic Protocols	
	Method Connect arguments	
	– Method Disconnect arguments	
	– Method Transfer arguments	
	– EddDataTypeInfo DataType Structure	
	- EddDataTypeEnum Values	
	– Ludbata rypeLndin values – Method SetAddress arguments	
	- Connect service arguments	
	-	
	– Method Transfer arguments	
	- Method SetAddress arguments	
	- Elements of GenericNetworkT	
	- Attributes of GenericConnectionPointT	
	- Elements of GenericConnectionPointT	
Table A.4	- Attributes of GenericIdentificationT	29
	- Attributes of TransferSendDataT	
Table B.2	- Elements of TransferSendDataT	31
Table B.3	– Elements of EddDataTypeInfoListT	31
Table B.4	- Attributes of EddDataTypeInfoT	32
Table B.5	– Enumerations of EddDataTypeT	33
Table B.6	- Attributes of TransferResultDataT	33

#### INTERNATIONAL ELECTROTECHNICAL COMMISSION

#### FIELD DEVICE INTEGRATION (FDI) -

#### Part 100: Profiles - Generic protocols

#### **FOREWORD**

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International Standard IEC 62769-100 has been prepared by subcommittee 65E: Devices and integration in enterprise systems, of IEC technical committee 65: Industrial-process measurement, control and automation.

FCG TS62769-100 Edition 1.1, *Field Device Integration Part 100: Profiles – Generic Protocols*, a specification of the FieldComm Group, PROFIBUS Nutzerorganisation e. V., OPC Foundation and FDT Group, serves as a basis for the elaboration of this standard.

The text of this International Standard is based on the following documents:

FDIS	Report on voting
65E/739/FDIS	65E/743/RVD

Full information on the voting for the approval of this International Standard can be found in the report on voting indicated in the above table.

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- 5 -

This document has been drafted in accordance with the ISO/IEC Directives, Part 2.

A list of all parts in the IEC 62769 series, published under the general title *Field Device Integration (FDI)*, can be found on the IEC website.

The committee has decided that the contents of this document will remain unchanged until the stability date indicated on the IEC website under "http://webstore.iec.ch" in the data related to the specific document. At this date, the document will be

- · reconfirmed,
- withdrawn,
- · replaced by a revised edition, or
- amended.

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#### FIELD DEVICE INTEGRATION (FDI) -

#### Part 100: Profiles - Generic protocols

#### 1 Scope

This part of IEC 62769 specifies an FDI profile of IEC 62769 for generic protocols. That means that all interfaces are defined, and a host can add support for more protocols without changing its implementation. Nevertheless, there are some protocol-specific definitions (PSD) that need to be specified per protocol using this profile. Annex C specifies what PSDs need to be defined per protocol so that FDI Device Packages, FDI Communication Packages for Gateways and FDI Communication Servers, FDI Communication Servers, Gateways and Devices supporting such a protocol can work together in a host not aware about this specific protocol.

NOTE A host not using an FDI Communication Server but a proprietary mechanism for communication defines its own means to deal with this profile to support several protocols without changing its implementation. This is specific to the proprietary way how the communication driver is bound to the host.

#### 2 Normative references

The following documents are referred to in the text in such a way that some or all of their content constitutes requirements of this document. For dated references, only the edition cited applies. For undated references, the latest edition of the referenced document (including any amendments) applies.

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IEC 61804 (all parts), Function blocks (FB) for process control and Electronic Device Description Language (EDDL)

IEC 61804-3, Function blocks (FB) for process control and Electronic Device Description Language (EDDL) – Part 3: EDDL syntax and semantics

IEC 62541-100:2015, OPC Unified Architecture - Part 100: OPC UA for Devices

IEC 62769-2, Field Device Integration (FDI) - Part 2: FDI Client

IEC 62769-4, Field Device Integration (FDI) – Part 4: FDI Packages

IEC 62769-5, Field Device Integration (FDI) – Part 5: FDI Information Model

IEC 62769-7, Field Device Integration (FDI) - Part 7: FDI Communication Devices

#### 3 Terms, definitions, abbreviated terms and conventions

For the purposes of this document, the terms and definitions given in IEC 61804 series, IEC 62541-100, IEC 62769-2, IEC 62769-4, IEC 62769-5 and IEC 62769-7 apply.

ISO and IEC maintain terminological databases for use in standardization at the following addresses:

- IEC Electropedia: available at http://www.electropedia.org/
- ISO Online browsing platform: available at http://www.iso.org/obp

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**-7-**

#### 3.1 Abbreviated terms

EDD electronic device description

EDDL Electronic Device Description Language (see IEC 61804)

FDI™ Field Device Integration™1

FCG FieldComm Group

XML Extensible Markup Language (see FCG TS62769-100, Edition 1.1, Field Device Integration Part 100: Profiles – Generic Protocols, available at https://fieldcommgroup.org)

#### 3.2 Conventions

#### 3.2.1 EDDL syntax

This document specifies content for the EDD component that is part of FDI Communication Packages. The specification content using EDDL syntax uses the font Courier New. The EDDL syntax is used for method signature, variable, data structure and component declarations.

#### 3.2.2 XML syntax

XML syntax examples use the font Courier New. The XML syntax is used to describe XML document schema.

Example: <xs:simpleType name="ExampleType">REVIEW

### 3.2.3 Capitalizations (standards.iteh.ai)

The IEC 62769 series uses capita<u>lized\_terms\_to\_emphasi</u>ze that these terms have an FDI-specific meaning. https://standards.iteh.ai/catalog/standards/sist/a0594268-c994-4be0-bdde-

24ecdb98bd69/sist-en-iec-62769-100-2021

Some of these terms use an initialism as a prefix, for example:

- · FDI Client, or
- FDI Server.

Some of these terms are compound terms, such as:

- · Communication Servers, or
- Profile Package.

Parameter names or attributes are concatenated into a single term, where the original terms start in this term with a capital letter, such as:

- · ProtocolSupportFile or
- ProtocolType.

Parameter names or attributes can also be constructed by using an underscore character to concatenate two or more terms, such as:

- DEVICE REV or
- DEVICE\_MODEL

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